



Module 19

Activity: Bluetooth Low Energy



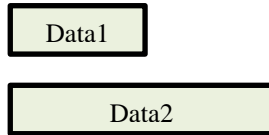
Activity: Bluetooth Low Energy

Question 1

Write code to add a service with one read and one write characteristic.

The read variable, Data1, is 16 bits

The write variable, Data2, is 32 bits

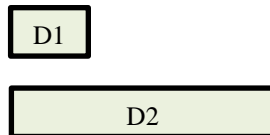


Question 2

Write code to add a service with two read characteristics.

The first read variable, D1, is 8 bits

The second read variable, D2, is 32 bits

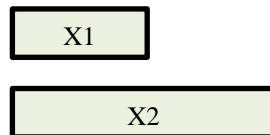


Question 3

Write code to add a service with two write characteristics.

The first write variable, X1, is 16 bits

The second read variable, X2, is 32 bits



Question 4

Write code to add a service with one notify characteristic. If active notify the client when the LaunchPad switch 1 changes (falling and rising edges). Use GPIO interrupts so the notification occurs in the ISR.

Question 5

Write code to add a service

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